Wuxi Unigroup Microelectronics Co.,Ltd

700V Super-Junction Power MOSFET

DESCRIPTION

700V super-junction Power MOSFET

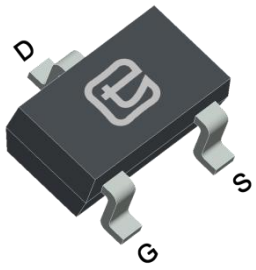
Super-junction power MOSFET is a revolutionary technology for high voltage power MOSFETs，designed according to the SJ principle. The SJ MOSFET is a price-performance optimized product enabling to target cost sensitive applications in Consumer and Lighting markets，designed by Wuxi Unigroup Microelectronics Company.

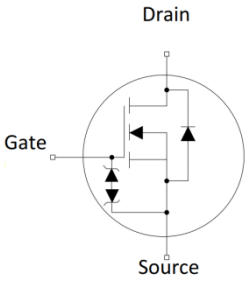
FEATURES

- Very low FOM $R_{DS(on)} \times Q_g$
- 100% avalanche tested
- RoHS compliant

APPLICATIONS

- Switch Mode Power Supply (SMPS)
- Uninterruptible Power Supply (UPS)
- Power Factor Correction (PFC)





RoHS

Device Marking and Package Information

Device	Package	Marking
TPY70R1K6MB	SOT-223	70R1K6M

Key Performance Parameters

Parameter	Value	Unit
V_{DS} @ $T_{j,max}$	700	V
$R_{DS(on),max}$	1.6	Ω
I_D	3	A
$Q_{g,typ}$	7.2	nC
I_{DM}	9	A
ESD class（HBM）	1C	

Absolute Maximum Ratings T_C = 25ºC, unless otherwise noted				
Parameter		**Symbol**	**Value**	**Unit**
Drain-Source Voltage (V_{GS} = 0V)		V_{DSS}	700	V
Continuous Drain Current	T_C = 25ºC	I_D	3	A
	TC = 100ºC		1.8	
Pulsed Drain Current (note1)		I_{DM}	9	A
Gate-Source Voltage		V_{GSS}	±20	V
Single Pulse Avalanche Energy (note2)		E_{AS}	26	mJ
Repetitive Avalanche Energy (note2)		E_{AR}	0.10	mJ
Avalanche Current		I_{AR}	0.6	A
MOSFET dv/dt ruggedness, V_{DS} = 0...480V		dv/dt	50	V/ns
Power Dissipation		P_D	6.2	W
Continuous Body Diode Current		I_S	2.5	A
Pulsed Diode Forward Current (note1)		I_{SM}	33	
Reverse diode dv/dt (note3)		dv/dt	15	V/ns
Maximum diode commutation speed (note3)		di_f/dt	500	A/us
Operating Junction and Storage Temperature Range		T_J, T_{stg}	-55~+150	ºC

Thermal Resistance			
Parameter	**Symbol**	**Value**	**Unit**
Thermal Resistance, Junction-to-Case	R_{thJC}	20	ºC/W
Thermal Resistance, Junction-to-Ambient	R_{thJA}	160	

Specifications T_J = 25ºC, unless otherwise noted						
Parameter	**Symbol**	**Test Conditions**	**Value**			**Unit**
			Min.	**Typ.**	**Max.**	
Static						
Drain-Source Breakdown Voltage	$V_{(BR)DSS}$	V_{GS} = 0V, I_D = 250μA	700	--	--	V
Zero Gate Voltage Drain Current	I_{DSS}	V_{DS} = 700V, V_{GS} = 0V, T_J = 25ºC	--	--	1	μA
		V_{DS} = 700V, V_{GS} = 0V, T_J = 150ºC	--	--	100	
Gate-Source Leakage	I_{GSS}	V_{GS} = ±20V	--	--	±1	μA
Gate-Source Threshold Voltage	$V_{GS(th)}$	V_{DS} = V_{GS}, I_D = 250μA	2.5	--	4.5	V
Drain-Source On-Resistance	$R_{DS(on)}$	V_{GS} = 10V, I_D = 1A	--	1.4	1.6	Ω
Gate resistance	R_G	f = 1.0MHz open drain	--	44	--	Ω
Dynamic						
Input Capacitance	C_{iss}	V_{GS} = 0V, V_{DS} = 100V, f = 1.0MHz	--	239	--	pF
Output Capacitance	C_{oss}		--	10	--	
Reverse Transfer Capacitance	C_{rss}		--	1	--	
Total Gate Charge	Q_g	V_{DD} = 560V, I_D = 3A, V_{GS} = 10V	--	7.2	--	nC
Gate-Source Charge	Q_{gs}		--	1.3	--	
Gate-Drain Charge	Q_{gd}		--	3.4	--	
Turn-on Delay Time	$t_{d(on)}$	V_{DD} = 400V, I_D = 3A, R_G = 25Ω	--	57	--	ns
Turn-on Rise Time	t_r		--	63	--	
Turn-off Delay Time	$t_{d(off)}$		--	111	--	
Turn-off Fall Time	t_f		--	53	--	
Drain-Source Body Diode Characteristics						
Body Diode Voltage	V_{SD}	T_J = 25ºC, I_{SD} = 1A, V_{GS} = 0V	--	0.9	1.2	V
Reverse Recovery Time	t_{rr}	V_R = 400V, I_F = 3A, di_F/dt = 100A/μs	--	200	--	ns
Reverse Recovery Charge	Q_{rr}		--	0.9	--	μC
Peak Reverse Recovery Current	I_{rrm}		--	8	--	A

Notes

1. Repetitive Rating: Pulse width limited by maximum junction temperature
2. I_{AS} = 0.6A, V_{DD} = 50V, R_G = 25Ω, Starting T_J = 25°C
3. Identical low side and high side switch with identical R_G

Typical Characteristics T_J = 25ºC, unless otherwise noted

Figure 1. Output Characteristics

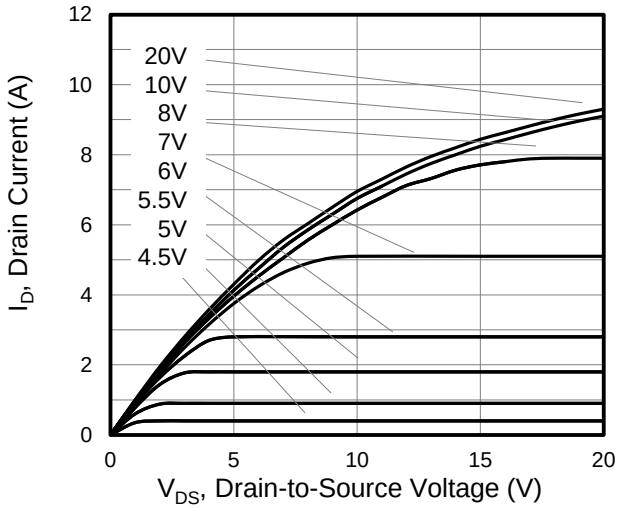


Figure 2. Transfer Characteristics

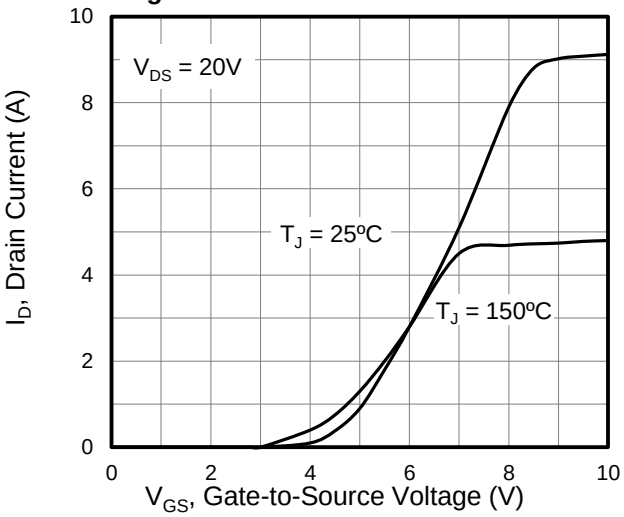


Figure 3. On-Resistance vs. Drain Current

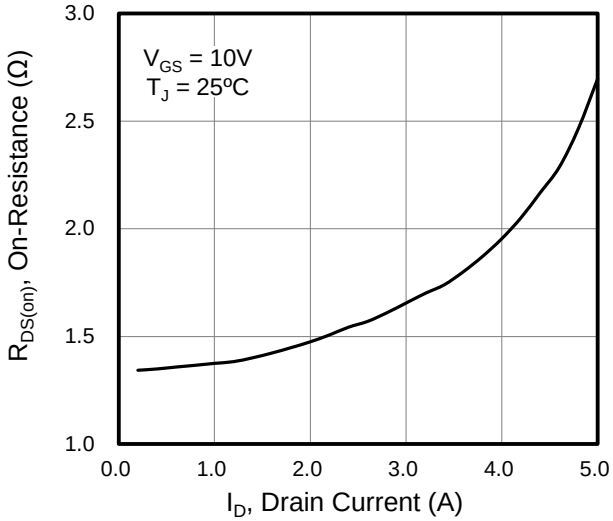


Figure 4. Capacitance

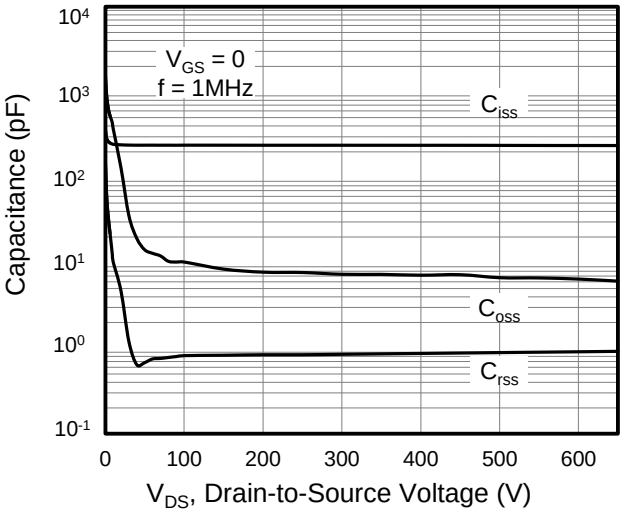


Figure 5. Gate Charge

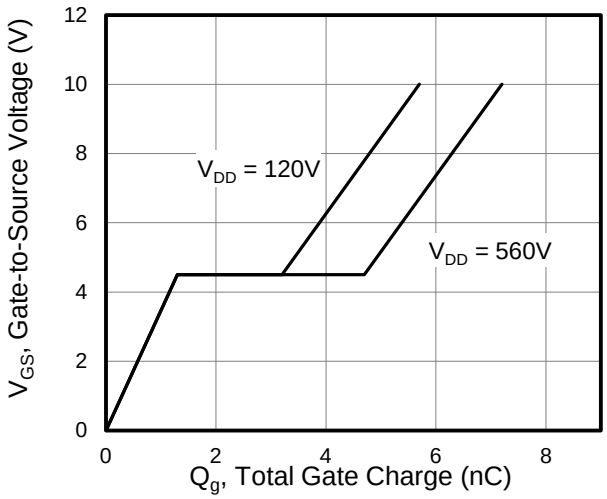
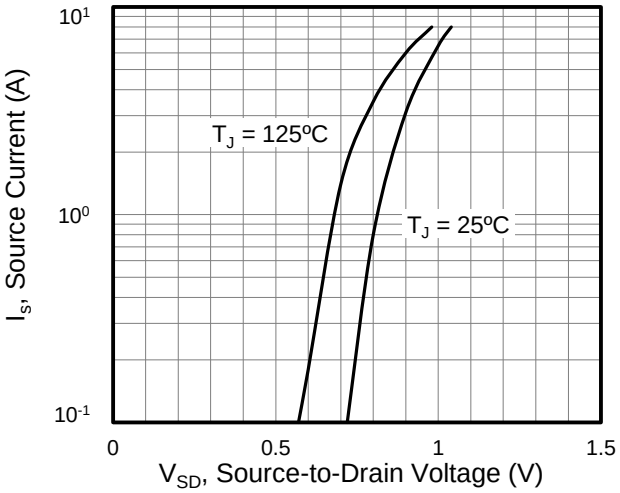


Figure 6. Body Diode Forward Voltage



Typical Characteristics T_J = 25ºC, unless otherwise noted

Figure 7. On-Resistance vs. Junction Temperature

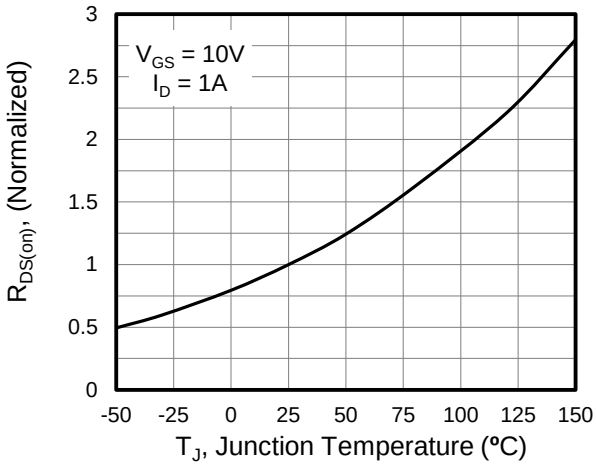


Figure 8. Breakdown voltage vs. Junction Temperature

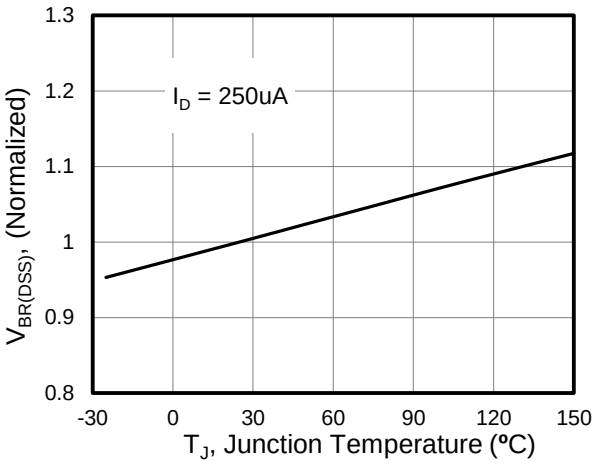


Figure 9. Transient Thermal Impedance for SOT-223

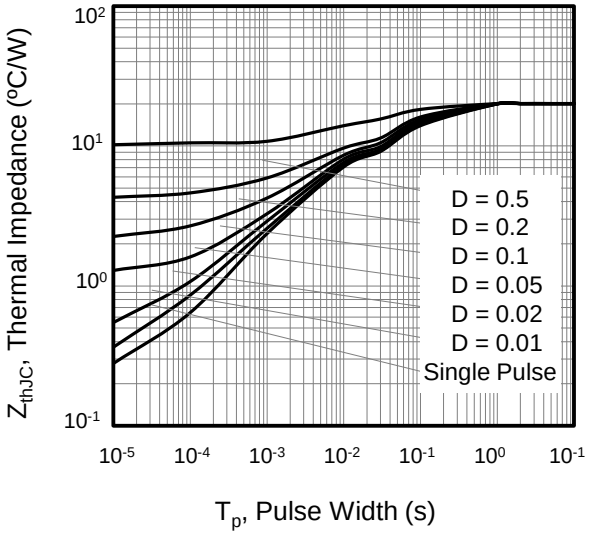


Figure 10. Safe operation area for SOT-223

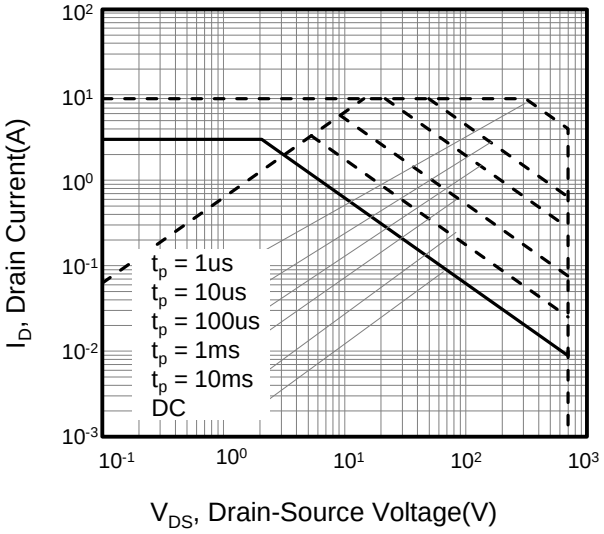


Figure A：Gate Charge Test Circuit and Waveform

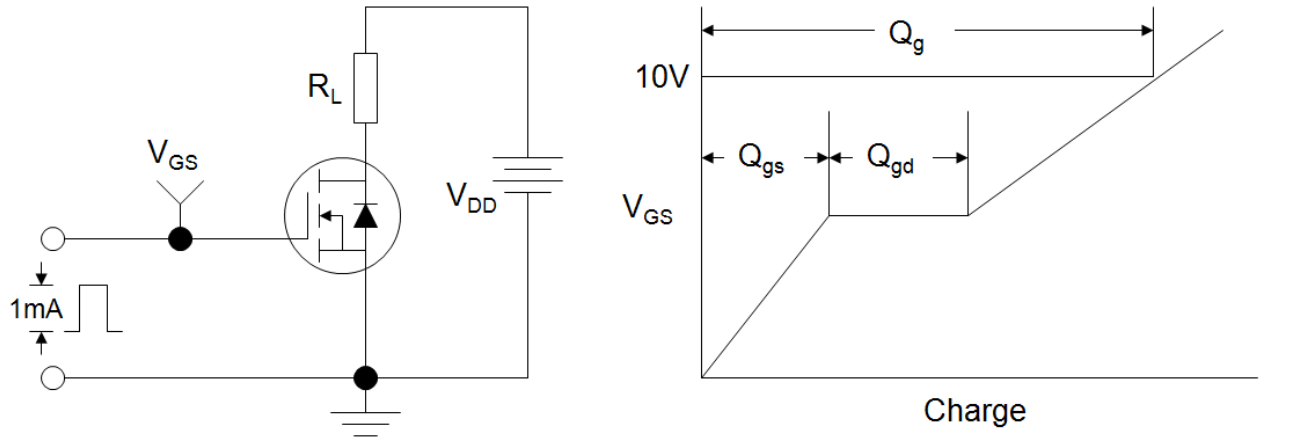


Figure B：Resistive Switching Test Circuit and Waveform

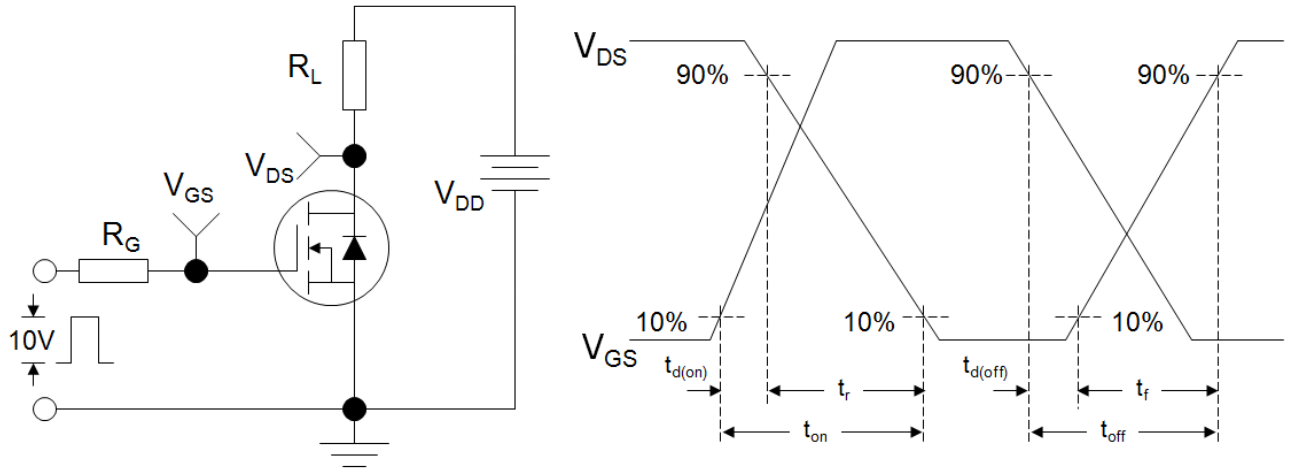
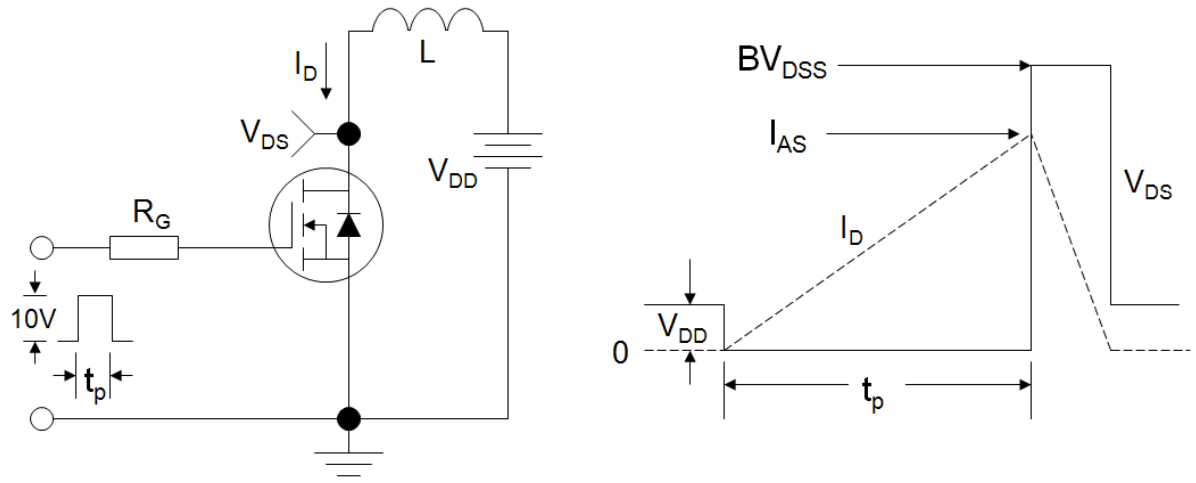
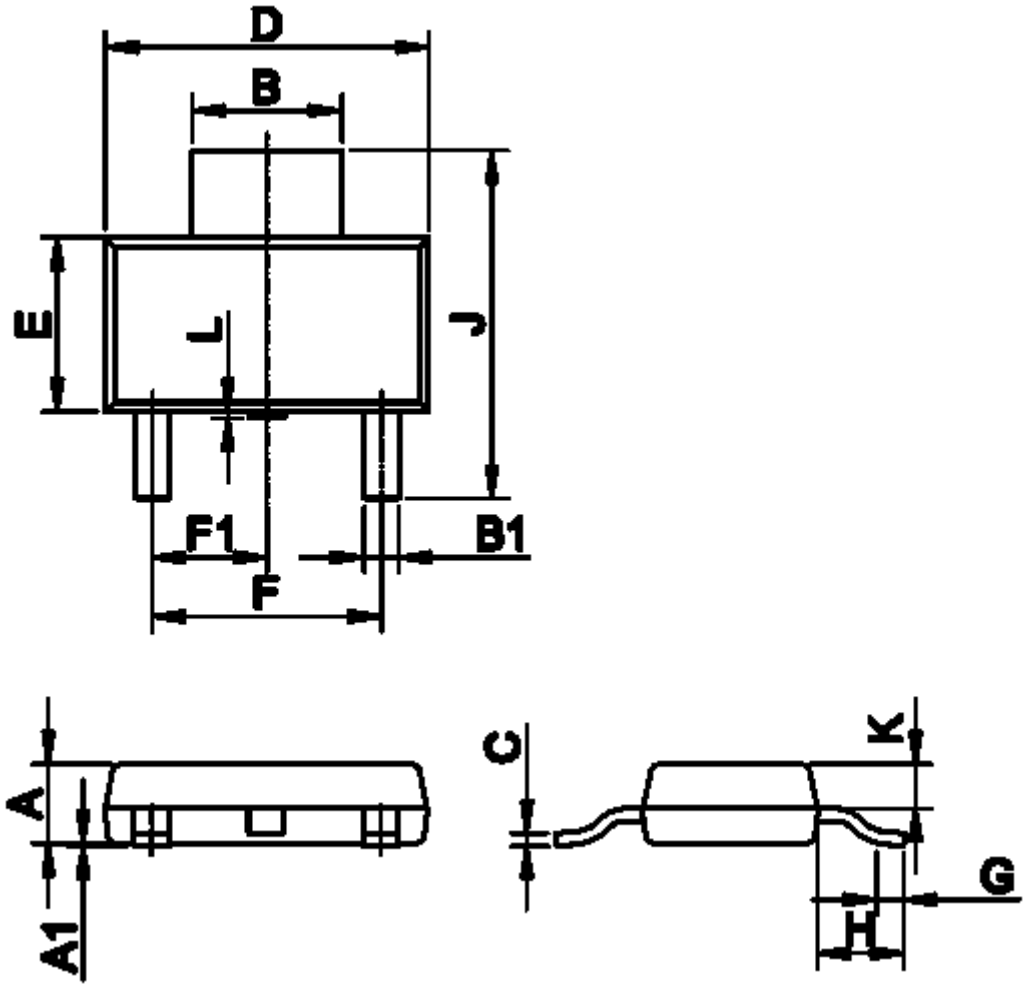


Figure C：Unclamped Inductive Switching Test Circuit and Waveform



SOT-223



Unit:mm			
Symbol	Min.	Typ.	Max.
A	1.50	1.60	1.80
A1	0.01	0.06	0.10
B	2.90	3.00	3.10
B1	0.60	0.07	0.80
C	0.22	0.254	0.32
D	6.30	6.50	6.70
E	3.30	3.50	3.70

Unit:mm			
Symbol	Min.	Typ.	Max.
F		4.60	
F1		2.30	
G	0.70	0.90	1.10
H	1.50	1.75	2.00
J	6.70	7.00	7.30
K		0.90	
L	0	0.10	0.20

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